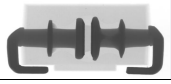
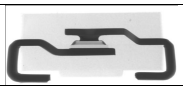
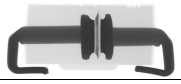
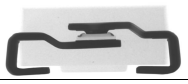
RECTRON SEMICONDUCTOR

EOL Notification
Document #: EOL for SMX Package FFM 10XW and HFM 10XW Series
Issue Date: 2026/8/21
PCN#: 20260821001

Title of Change:	EOL for SMX Package FFM10XW and HFM10XW Series
Proposed first ship date	2026、8
Contact information:	Please contact Rectron Sales Office or visit www.rectron.com for nearest contact information.
Samples:	Please contact Rectron Sales Office or visit www.rectron.com for nearest contact information. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Please contact Rectron Sales Office or visit www.rectron.com for nearest contact information.
Type of notification:	This EOL notice is issued 180 days prior to implementation. Rectron shall deem this change as accepted unless a written objection is raised within 30 days from the date of receipt of this notice. For contact information, please visit www.rectron.com to obtain the latest contact details.
Change Part Identification:	EOL
Change Category:	☐Material ☐Machine/Tooling ☐Method ☐Manufacture site ☐Man
Change Sub-Category(s):	☐DICE ☐Lead Frame ☐Solder Past ☐Epoxy
Last order date for previous version	2026/8/21
Description and Purpose:	FFM Series: 1.The original OJ chip cannot be produced normally due to environmental protection policy ; 2.Process iteration, production-line consolidation, replacement by new-generation technology, and improvement of long-term reliability; 3.EOL (End-of-Life) will be implemented for this part number which adopts old OJ die process. To unify the manufacturing platform and improve long-term product reliability as well as process consistency, the company is carrying out product-line process rationalization, phasing out old OJ junction-coating die process and fully migrating to the GPP glass passivation die process. 4.Products adopting the GPP process feature superior high-temperature reverse-bias reliability, lower reverse leakage current and better resistance to environmental stress. They serve as compatible replacements. Accordingly, parts built with the original OJ process will no longer be manufactured, and the formal EOL process is initiated. FFM HFM Series: Due to strategic product line adjustments and capacity optimization for legacy SMX package assembly lines, continuous mass production of FFM10XW and HFM10XW series in SMX package has been discontinued, and new orders will no longer be accepted.

Point:	**Type**	**EOL Before**	**Recommended Replacement Part(s)**
EOL:		SMX O/J FFM10XW Series	SMA GPP FFM10X Series
			
		SMX GPP HFM10XW Series	SMA GPP HFM10X Series
			

Electrical Characteristic Summary:	* High reliability * Low leakage current * Glass passivated junction * SMA is a mainstream industry-standard package featuring sufficient production capacity and improved supply stability. * It enjoys mature SMT process compatibility and ensures stable electrical performance of the device.
List of Affected Parts:	Refer to the list below

Part Number	**Suggest New Part Number**	**Addition**	**Mark**
HFM102W-W-MA1	HFM102-W-MA1		
HFM102W-W-ES1	HFM102-W-ES1		
HFM102W-W-OX1	HFM102-W-OX1		
HFM102W-W-EX1	HFM102-W-EX1		
HFM102W-T	HFM102-T		
HFM103W-W-MA1	HFM103-W-MA1		
HFM105W-W-HL1	**HFM105-W-HL1**		
HFM105W-T-TN1	HFM105-T-TN1		
HFM105W-T-TN2	HFM105-T-TN2		
HFM105W-W-MA1	HFM105-W-MA1		
HFM105W-W	HFM105-W		
HFM106W-W-TN1	HFM106-W-TN1		
HFM106W-W	HFM106-W		
HFM106W-W-OX1	HFM106-W-OX1		
HFM107W-T-TN1	HFM107-T-TN1		
HFM107W-T	HFM107-T		
FFM104W-W	FFM104-W		
FFM104W-W-HL1	FFM104-W-HL1		
FFM104W-W-LGHZ	FFM104-W-LGHZ		
FFM104W-W-LGPT	FFM104-W-LGPT		
FFM104W-T-GL	FFM104-T-GL		
FFM104W-T	FFM104-T		
FFM105W-W-HL1	**FFM105-W-HL1**		
FFM105W-W	FFM105-W		
FFM105W-W-MA1	FFM105-W-MA1		

Cust. Comments :